Thermal Monitor

FEATURES

- On-Chip Temperature Transducer
- Temperature Comparator Gives Threshold Temperature Alarm
- Power Reference Permits Airflow Diagnostics
- Precision 2.5V Power Reference Permits Airflow Diagnostics
- Transducer Output is Easily Scaled for Increased Sensitivity
- Low 2.5mA Quiescent Current

BLOCK DIAGRAM

DESCRIPTION

The UC1730 family of integrated circuit devices are designed to be used in a number of thermal monitoring applications. Each IC combines a temperature transducer, precision reference, and temperature comparator allowing the device to respond with a logic output if temperatures exceed a user programmed level. The reference on these devices is capable of supplying in excess of 250mA of output current – by setting a level of power dissipation the rise in die temperature will vary with airflow past the package, allowing the IC to respond to airflow conditions

These devices come in an 8-Pin DIP, plastic or ceramic, a 5-Pin TO-220 or a PLCC-20 version. In the 8-Pin version, a PTAT (proportional to absolute temperature) output reports die temperature directly. This output is configured such that its output level can be easily scaled up with two external gain resistors. A second PTAT source is internally referenced to the temperature comparator. The other input to this comparator can then be externally programmed to set a temperature threshold. When this temperature threshold is exceeded an alarm delay output is activated. Following the activation of the delay output, a separate open collector output is turned on. The delay pin can be programmed with an external RC to provide a time separation between activation of the delay pin and the alarm pin, permitting shutdown diagnostics in applications where the open collector outputs of multiple parts are wire OR'ed together.

The 5-Pin version in the TO-220 package is well suited for monitoring heatsink temperatures. Enhanced airflow sensitivities can be obtained with this package by mounting the device to a small heatsink in the airstream. This version of the device does not include the PTAT output or the open collector alarm output.

PTAT REFERENCE **BUFFER AMPLIFIER** THERMAL PTAT+ 5 (NA) COUPLING 2.5V 2.5V REFERENCE PTAT- 6 (NA) (3) 4] GND PTAT VOLTAGES 5 mV/°K **TEMPERATURE** COMPARATOR ALARM 1 (4) 5kΩ ALARM THRESHOLD ALARM **BUFFER** 1.25V

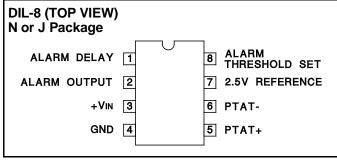
Pin numbers shown for 8-Pin DIP, () number for 5-Pin TO-220.

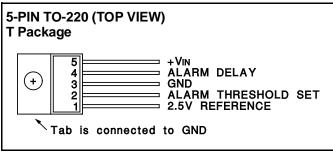
ABSOLUTE MAXIMUM RATINGS

| ABOULUI III IA TIII IO |
|---|
| Input Supply Voltage, (+VIN) |
| Alarm Output Voltage (8-Pin Version Only) 40V |
| Alarm Delay Voltage |
| Alarm Threshold Set Voltage |
| 2.5V Reference Output Current |
| Alarm Output Current (8-Pin Version Only) 0 mA |
| Power Dissipation at T _A = 25°C (Note 2) 1000 mW |
| Power Dissipation at Tc = 25°C (Note 2) 2000 mW |
| Thermal Resistance Junction to Ambient |
| N, 8-Pin Plastic DIP |
| J, 8-Pin Ceramic DIP |
| |

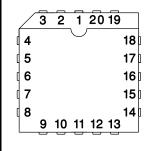
| T, 5-Pin Plastic DIP TO-220 65°C/W |
|---|
| Thermal Resistance Junction to Case |
| N, 8-Pin Plastic DIP |
| J, 8-Pin Ceramic DIP |
| T, 5-Pin Plastic TO-220 |
| Operating Junction Temperature55°C to +150°C |
| Storage Temperature65°C to +150°C |
| Lead Temperature (Soldering, 10 Seconds) 300°C |
| Note 1: Voltages are referenced to ground. Currents are posi- |
| tive into, negative out of, the specified terminals. |
| Note 2: Consult Packaging section of Databook for thermal |
| limitations and considerations of package. |

CONNECTION DIAGRAMS





PLCC-20 (TOP VIEW) Q Package



| PACKAGE PIN FUNCTION | | | |
|----------------------|-------|--|--|
| FUNCTION | PIN | | |
| N/C | 1-3 | | |
| ALARM DELAY | 4 | | |
| ALARM OUTPUT | 5 | | |
| +VIN | 6 | | |
| GND | 7 | | |
| N/C | 8-13 | | |
| PTAT+ | 14 | | |
| PTAT- | 15 | | |
| 2.5V REFERENCE | 16 | | |
| 2.5V REFERENCE | 17 | | |
| ALARM | 18 | | |
| THRESHOLD SET | | | |
| N/C | 19-20 | | |
| THRESHOLD SET | | | |

ELECTRICAL CHARACTERISTICS: Unless otherwise stated, these specifications apply for T_J = 0°C to +100°C for the UC3730, -25°C to +100°C for the UC2730 and -55°C to +125°C for the UC1730, +VIN = +5V, and PTAT = 0V. TA = T_J.

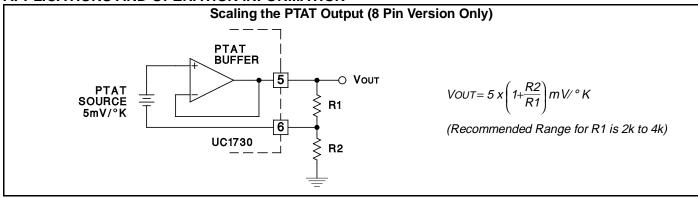
| PARAMETERS | TEST CONDITIONS | MIN | TYP | MAX | UNITS |
|----------------------------------|--|-------|-------|-------|-------|
| INPUT SUPPLY | | | | | |
| Supply Current | +VIN = 35V | | 2.8 | 4.0 | mA |
| | +VIN = 5V | | 2.3 | 3.5 | mA |
| REFERENCE | | | | | |
| Output Voltage | T _J = 25°C | 2.475 | 2.5 | 2.525 | V |
| | Over Temperature | 2.46 | | 2.54 | V |
| Load Regulation | IOUT = 0 to 250mA | | 8.0 | 25 | mV |
| Line Regulation | +VIN = 5 to 25V | | 1.0 | 5.0 | mV |
| TEMPERATURE COMPARATOR | | | | | |
| Temperature Comparator Threshold | at 300°K (26.85°C), Nominally 5mV/°K, VINPUT High to Low | 1.475 | 1.50 | 1.525 | V |
| Temperature Error | | -10 | | 10 | °C |
| Threshold Line Regulation | +VIN = 5 to 25V | | 0.005 | 0.02 | %/V |
| Temperature Linearity | Note 2 | | 2.0 | 5.0 | °C |
| Threshold Hysteresis | | 3.0 | 8.0 | 15 | mV |
| Input Bias Current | VINPUT at 1.5V | -0.5 | -0.1 | | μΑ |
| Max Output Current | VOUT = 1V | 1.2 | 3.0 | | mA |
| Output Sat Voltage | Ιουτ = 100μΑ | | 0.05 | 0.25 | V |

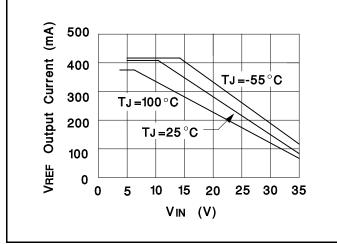
ELECTRICALUnless otherwise stated, these specifications apply for T_J = 0°C to +100°C for the UC3730, **CHARACTERISTICS (cont):** -25°C to +100°C for the UC2730 and -55°C to +125°C for the UC1730, +VIN = +5V, and PTAT— = 0V. TA = T_J.

| PARAMETERS | TEST CONDITIONS | MIN | TYP | MAX | UNIT |
|------------------------------------|--------------------------------------|-------|------|------|------|
| TEMPERATURE COMPARATOR (co | nt.) | - | • | • | • |
| Output Leakage Current | Vout = 1V | | 0.01 | 1.0 | μΑ |
| PTAT BUFFER (8-Pin N, or J Version | Only) | _ | | | |
| Output Voltage | at 300°K (26.85°C), Nominally 5mV/°K | 1.460 | 1.50 | 1.54 | V |
| | In 10X Config. + VIN = 25V | 14.6 | 15 | 15.4 | V |
| Temperature Error | | -12 | | 12 | °C |
| Temperature Linearity (Note 2) | | | 2.0 | 5.0 | °C |
| Line Regulation | +VIN = 5 to 25V | | 0.02 | 0.04 | %/V |
| Load Regulation | IOUT = 0 to 2mA | | 1.0 | 3.0 | mV |
| Dropout Voltage | PTAT + TO +VIN | | 1.9 | 2.5 | V |
| Input Bias Current at PTAT- Input | | -3.0 | -1.0 | | μΑ |
| ALARM BUFFER COMPARATOR (8- | -Pin N, or J Version Only) | - | | | |
| Threshold Voltage (VTH) | Alarm Delay Input Low to High | 1.1 | 1.2 | 1.3 | V |
| Threshold Hysteresis Voltage | Alarm Delay Voltage > VTH | | 100 | 250 | mV |
| Input Bias Current | Alarm Delay Voltage < VTH | | 0.1 | 0.5 | μΑ |
| Max Output Current | Vout = 1V | 7.0 | 15 | | mA |
| Output Sat Voltage | IOUT = 3mA | | 0.25 | 0.45 | V |
| Output Leakage | Vout = 35V | | 0.1 | 2.0 | μΑ |

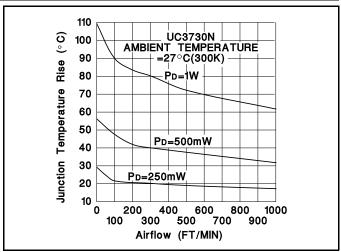
Note 2: This parameter is guaranteed by design and is not tested in production.

APPLICATIONS AND OPERATION INFORMATION



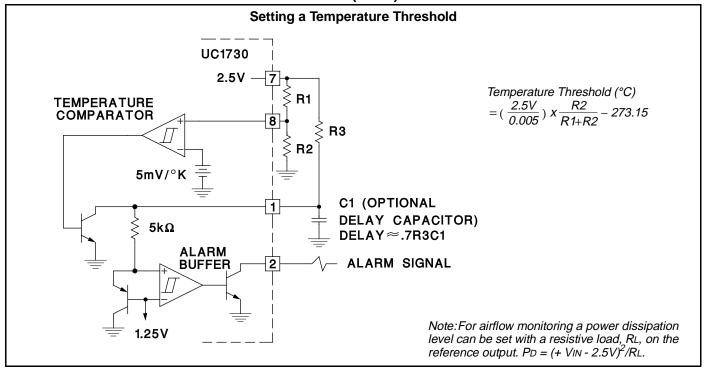


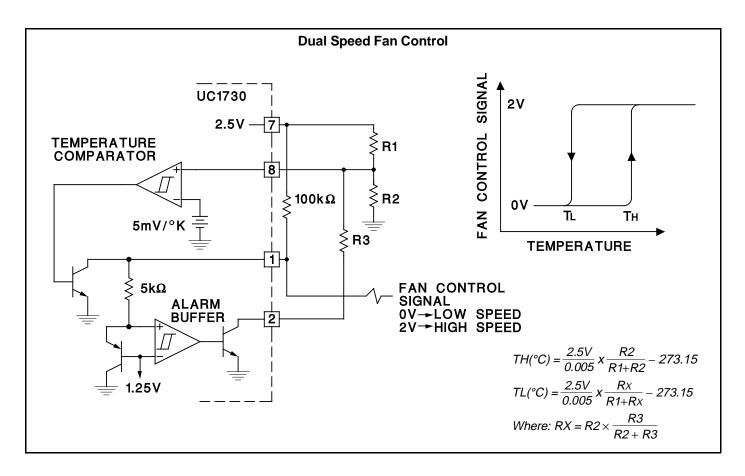
VREF Maximum Output Current vs Input Supply



Junction Temperature Rise vs Airflow UC3730N (8-Pin Plastic Dip)

APPLICATIONS AND OPERATION INFORMATION (Cont.)





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